## (19) World Intellectual Property Organization International Bureau





(43) International Publication Date 12 May 2005 (12.05.2005)

PCT

## (10) International Publication Number WO 2005/043245 A3

(51) International Patent Classification7: C11D 11/00, 7/08, 7/10

G03F 7/42,

(21) International Application Number:

PCT/US2004/034541

(22) International Filing Date: 20 October 2004 (20.10.2004)

(25) Filing Language:

(26) Publication Language:

English

(30) Priority Data:

29 October 2003 (29.10.2003) 60/515,234

- (71) Applicant (for all designated States except US): MALLINCKRODT BAKER INC. [US/US]; 675 McDonnell Boulevard, P.O. Box 5840, St. Louis, MO 63134 (US).
- (72) Inventor; and
- (75) Inventor/Applicant (for US only): SKEE, David, C. [US/US]; 3192 Rambeau Road, Bethlehem, PA 18020 (US).
- (74) Agents: REBMAN, Christine, M. et al.; Mallinckrodt Inc., 675 McDonnell Boulevard, P.O. Box 5840, St. Louis, MO 63134 (US).
- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM,

AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

## Published:

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments
- (88) Date of publication of the international search report: 25 August 2005

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: ALKALINE, POST PLASMA ETCH/ASH RESIDUE REMOVERS AND PHOTORESIST STRIPPING COMPOSI-TIONS CONTAINING METAL-HALIDE CORROSION INHIBITORS

(57) Abstract: The invention provides alkaline compositions useful in the microelectronics industry for stripping or cleaning semiconductor wafer substrates by removing photoresist residues and other unwanted contaminants. The compositions contain (a) one or more bases and (b) one or more metal corrosion inhibiting metal halides of the formula: WzMXy where M is a metal selected from the group Si, Ge, Sn, Pt, P, B, Au, Ir, Os, Cr, Ti, Zr, Rh, Ru, and Sb; X is a halide selected from F, CI, Br and I; W is selected from H, to an alkali or alkaline earth metal, and a metal ion-free hydroxide base moiety; y is a numeral of from 4 to 6 depending on the metal halide; and z is a numeral of 1, 2 or 3.

